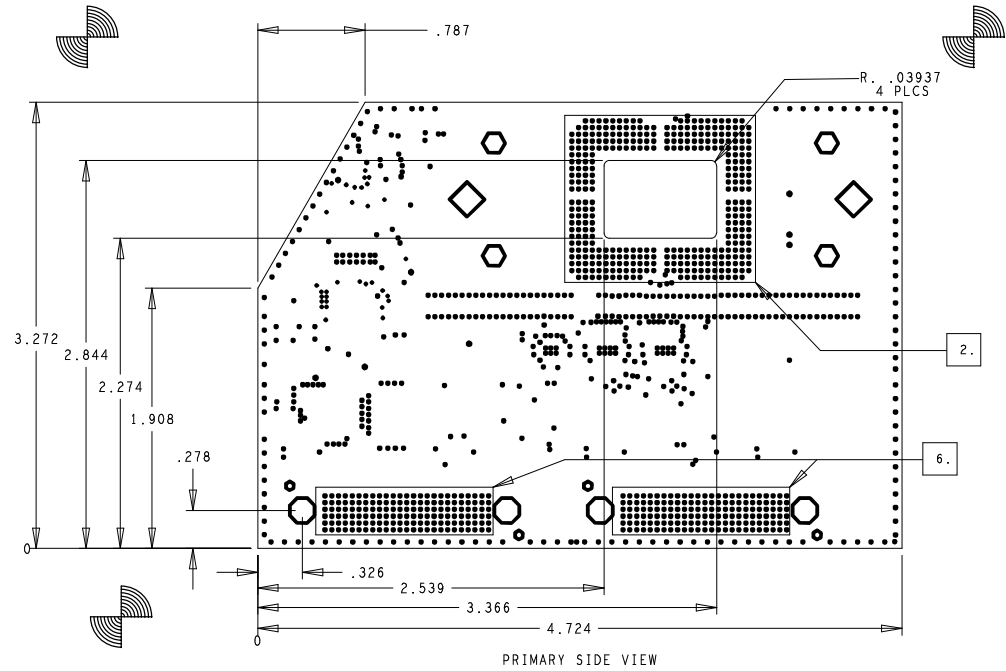


DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+3.0/-10.0	PLATED	32
•	12.0	+3.0/-12.0	PLATED	1129
•	24.0	+3.0/-3.0	PLATED	8
⬡	166.0	+3.0/-3.0	PLATED	4
•	66.0	+3.0/-3.0	NON-PLATED	4
⬢	182.0	+3.0/-3.0	NON-PLATED	4
◊	256.0	+3.0/-3.0	NON-PLATED	2



CUSTOMER NAME				
TEXAS INSTRUMENTS				
BOARD NAME		DESCRIPTION		
DLP041-DLPLCR67EVM		FABRICATION DRAWING		
BOARD NO.	REV	DATE	PRJ#	SH 17 OF 17
	A	09-28-2020	DLP041	

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010"
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT. RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

PROCESS NOTES:

- EXCEPT AS NOTED IN NOTE 2 AND 6, PLATE ALL EXPOSED AREAS WITH ELECTROLYTIC IMMERSION GOLD, NICKEL 100 MICROINCHES THK GOLD 2-6 MICROINCHES THK MIN.
- PLATE INDICATED PAD AREAS WITH 150 MICROINCHES MIN. LOW STRESS NICKEL UNDER 5-15 MICROINCHES GOLD HAVING A HARDNESS OF KNOOP14.
- APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC). COLOR: BLUE SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
- SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS, WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
- PLATE INDICATED PAD AREAS WITH ELECTROPLATED 100 MICROINCHES MIN. LOW STRESS NICKEL UNDER 30 MICROINCHES MIN. GOLD HAVING A HARDNESS OF KNOOP14.
- ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94-V0 UL REGISTERED MATERIAL ID NUMBER.

LAYER 1 PRIMARY SIDE - 1.5 OZ Cu Final, 6.25 MILS 50 OHMS SINGLE ENDED
3.86 MILS
LAYER 2 GND PLANE - 1 OZ Cu
6.00 MILS
LAYER 3 SIGNAL - .5 OZ Cu , 4.8 MIL WIDTH/7.2 MIL SPACING 100 OHMS DIFFERENTIAL. 5.75 MILS 50 OHMS SINGLE ENDED
6.48 MILS
LAYER 4 GND PLANE - 1 OZ Cu
5.00 MILS
LAYER 5 SIGNAL - .5 OZ Cu , 6 MILS 50 OHMS SINGLE ENDED
8.84 MILS
LAYER 6 SIGNAL - .5 OZ Cu , 6 MILS 50 OHMS SINGLE ENDED
5.00 MILS
LAYER 7 POWER PLANE - 1 OZ Cu
6.48 MILS
LAYER 8 SIGNAL - .5 OZ Cu , 4.8 MIL WIDTH/7.2 MIL SPACING 100 OHMS DIFFERENTIAL.
6.00 MILS
LAYER 9 GND PLANE - 1 OZ Cu
3.86 MILS
LAYER 10 SECONDARY SIDE - 1.5 OZ Cu Final, 6.25 MILS 50 OHMS SINGLE ENDED

IMPEDANCE TOLERANCE +/- 10%